

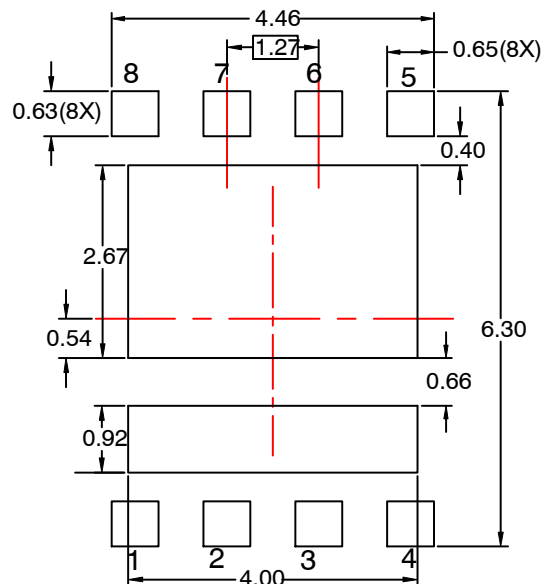
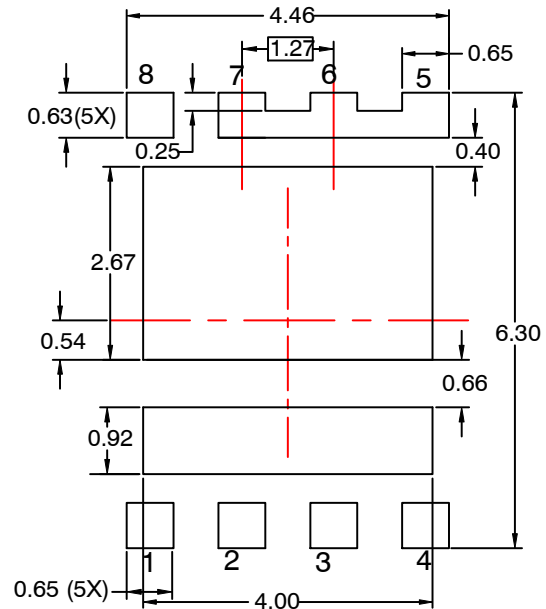
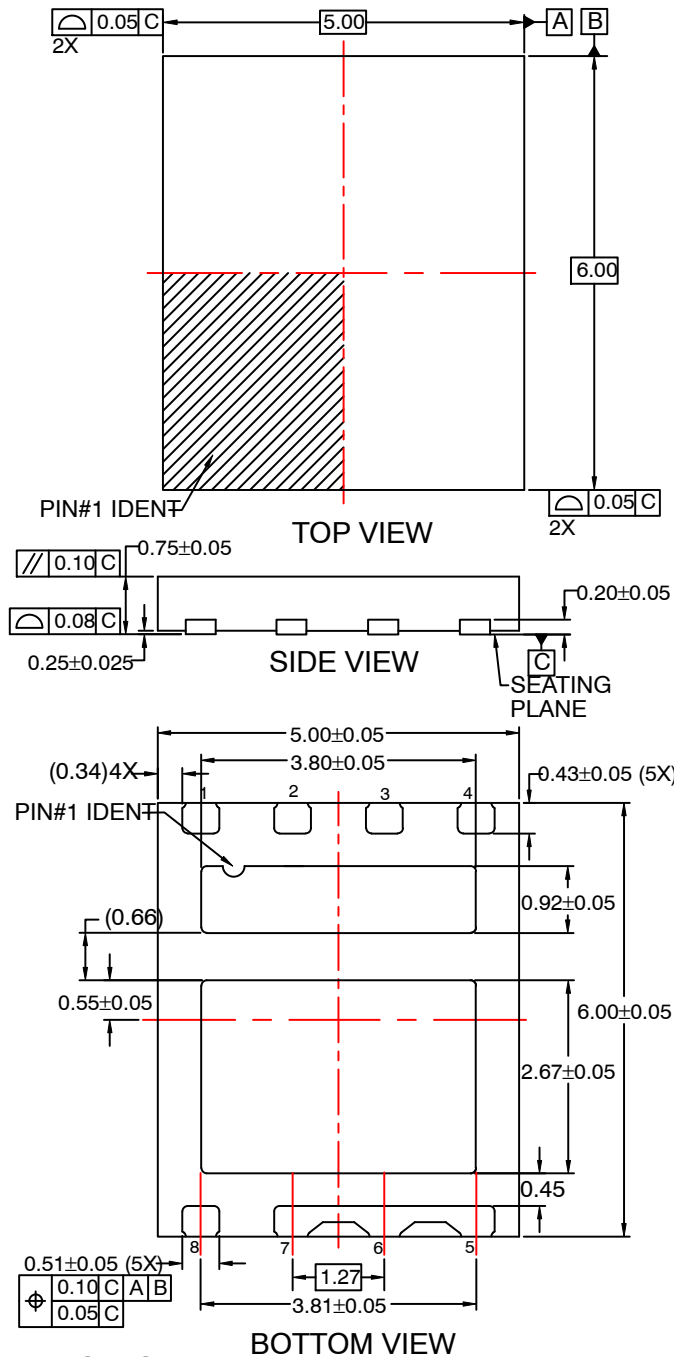
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



DFN8 5x6, 1.27P
CASE 506DR
ISSUE O

DATE 31 JUL 2016



- NOTES:**
 A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

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